

Addendum

MPC850R1UMAD
Rev. 1.6, 4/2004

Errata to the MPC850 Family
User's Manual, Rev. 1

This errata describes corrections to Revision 1 of the *MPC850 Family User's Manual* (Order No. MPC850UM, Rev. 1).

The MPC850 is a versatile, one-chip integrated microprocessor and peripheral combination. The MPC850 includes a high-performance embedded PowerPC™ core and a communications processor module (CPM).

1 Document Revision History

Table 1 provides a revision history for this document.

Table 1. Document Revision History

Rev. No.	Substantive Change(s)
1.4	Added new errata items from Section 1 (page 1-2), Section 27.7 (page 27-9), Section 27.21 (page 27-3), Section 31.4.1.2 (page 31-9), Section 34.1 (page 34-2), Section 35.2.1 (page 35-4), and Appendix F (page F-2).
1.5	Added new errata item for Section 18.6.3 (page 18-13).
1.6	Added new errata items for Section 21.2.1 (page 21-9), Section 22 (page 22-1), Section 22.16 (22-14), Section 31.4.1.2 (page 31-9), and Section B.3.1 (page B-4).

2 Document Errata

The section and page numbers of new errata items added since the last errata addendum are boldfaced.

Section/Page

1, 1-2

Changes

For the MPC850DSL part in Table 1-1, change 'Time-slot assigner, SMC2, and I²C are not supported.' to the following:

Time-slot assigner and I²C are not supported.



11.1.3.1, 11-3

Add the following note:

NOTE

The PLL loss of lock detection does not have a specification for the detection threshold. Therefore, it should be used solely as a debug tool and not in production systems. Characterization of the threshold value over temperature and operating voltages has shown that the threshold can be triggered when clock out to clock in phase differences are 1.8 ns or more.

11.3.1.1, 11-9

In Figure 11-8, change the field description for bit 2 to BBE (boot burst enable) and the field description for bit 15 to CLES (core little-endian swap).

Add the following description to Table 11-3:

Table 11-3. Hard Reset Configuration Word Field Descriptions

Bits	Name	Description
2	BBE	Boot burst enable 0 The boot device does not support bursting. 1 The boot device does support bursting.
15	CLES	Core little-endian swap. Defines core access operation following reset. 0 Big endian 1 Little endian

14.2.2.3, 14-8

Replace Table 14-2 with the following:

Table 14-2. XFC Capacitor Values Based on PLPRCR[MF]

MF Range	Minimum Capacitance	Maximum Capacitance	Unit
$1 \leq (MF + 1) \leq 4$	$XFC = [(MF + 1) \times 425] - 125$	$XFC = [(MF + 1) \times 590] - 175$	pF
$(MF + 1) > 4$	$XFC = (MF + 1) \times 520$	$XFC = (MF + 1) \times 920$	pF

15.4.1, 15-9

In Figure 16-6, BR0, add the following footnote:

Since the base address value is unknown at reset, program BR0 before programming OR0 to ensure proper operation.

15.4.2, 15-11

Replace the text after Figure 16-7 with the following:

At reset, OR0 has specific default values and is read-only, as shown in Figure 15-8. After reset, OR0 becomes R/W.

15.8.4, 15-55

Remove Section 15.8.4.1, "Address Incrementing for External Synchronous Bursting Masters."

18.6.3, 18-13

Remove Table 18-10 as well as the sentence before and the sentence after.

21.2.1, 21-9

In the MODE field (bits 28-31) of Table 21-2, V.14 RAM microcode is not supported. Thereby, mode 0111 should be reserved.

21.2.1, 21-9

In the MODE field (bits 28-31) of Table 21-2, DDCMP RAM microcode is not supported. Thereby, mode 1001 should be reserved.

22, 22-1

The last sentence in the last paragraph should be removed.

22.16, 22-14

In the RZS field (bit 7) of Table 22-9, for selection 1, the second sentence in the paragraph (making reference to V.14 applications) should be removed.

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Section, Page No.

Changes

27.7, 27-9	<p>Add superscript number 2 after PADDR1_H, PADDR1_M, PADDR1_L, TADDR_H, TADDR_M, and TADDR_L. Add the corresponding footnote 2 at the end of Table 27-1 with the following statement:</p> <p>The address should be written in little endian, not Motorola's big-endian format, that is, physical address 112233445566 should be written PADDR_L = 6655, PADDR_M = 4433, and PADDR_H = 2211. The TADDR should be written in the same way as the PADDR.</p>
27.21, 27-23	<p>In step 26, change the last sentence to read, "Then write 0x000E to TxBD[Data...]"</p>
31.4.1.2, 31-9	<p>In the last sentence of Example 1, change the order of the string for REV = 1 to the following:</p> <p>first j_klmn_r_stuv last</p> <p>In the last sentence of Example 3, change the order of the string for REV = 1 to the following:</p> <p>first r_stuv_ghij_klmn last</p>
34.1, 34-2	<p>Inside the second bullet, add a footnote at the end of the sentence that states:</p> <p>At power on reset, port pins are not defined in any particular state until CLKOUT is present for two clocks.</p>
34.3, 34-8	<p>In Table 34-6, add $\overline{RTS2}$ to PB18, PBPAR[DDn] = 1, and PBDIR[DRn] = 1.</p>
34.5.1.2, 34-18	<p>In Table 34-19, in the description of bits 3–15, add the following footnote to the definition of setting to 1 (The corresponding signal is an output):</p> <p>PD8 and PD10 will function as open drain.</p>
35.2.1, 35-4	<p>The first bullet should reflect SPS = 0, and the second bullet should reference SPS = 1.</p>
B.3.1, B-4	<p>In Table B-1, the row making reference to SCC in Profibus (seventeenth row) should be removed.</p>
Appendix B, B-4	<p>In Table B-1, add a column showing that USB is 24 Mbps at 25 MHz.</p>
Appendix F, F-2	<p>In Figure F-1, add a line over the block for SMC2 to show that it is supported.</p>
Global	<p>The following table is provided to clarify/correct the power-on reset value of many of the MPC850 registers and lists whether each register is affected by \overline{HRESET} and/or \overline{SRESET}.</p>
Legend:	<p>x or X = 'don't care' in either bits, nibbles, or the entire register. 0 = a single zero indicates the entire register is reset to zeros. () = isolates bits of a nibble of the register. ? = a don't care for POR, but if this register is affected by \overline{HRESET} or \overline{SRESET}, indicates that the value will remain the same as what it was before the reset occurred. NA = not applicable, indicates that this register has no POR value.</p>

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Section, Page No.

Changes

Table 2.

Register	POR Value	Affected by HRESET	Affected by SRESET
SIUMCR	01200000	Yes	No
SYPCR	FFFFFF07	Yes	No
SWSR	0	Yes	Yes
SIPEND	0000xxxx	Yes	Yes
SIMASK	0000xxxx	Yes	Yes
SIEL	0000xxxx	Yes	No
SIVEC	(xx11)(11xx)xxxxxx	Yes	Yes
TESR	XXXX0000	Yes	Yes
SDCR	0	Yes	No
PBR0	x	No	No
POR0	x	No	No
PBR1	x	No	No
POR1	x	No	No
PBR2	x	No	No
POR2	x	No	No
PBR3	x	No	No
POR3	x	No	No
PBR4	x	No	No
POR4	x	No	No
PBR5	x	No	No
POR5	x	No	No
PBR6	x	No	No
POR6	x	No	No
PBR7	x	No	No
POR7	x	No	No
PGCRA	0	Yes	No
PGCRBf	0	Yes	No
PSCR	x	No	No
PIPR	??00??00	Yes	Yes
PER	0	Yes	Yes
BR0	XXXXX(??00)0(000?)	Yes	No
OR0	0000FF4	Yes	No
BR1	XXXXXX(xx00)0	Yes	No

Table 2. (continued)

Register	POR Value	Affected by HRESET	Affected by SRESET
OR1	XXXXXXX(xx0)	Yes	No
BR2	XXXXXX(x00)0	Yes	No
OR2	XXXXXXX(xx0)	Yes	No
BR3	XXXXXX(x00)0	Yes	No
OR3	XXXXXXX(xx0)	Yes	No
BR4	XXXXXX(x00)0	Yes	No
OR4	XXXXXXX(xx0)	Yes	No
BR5	XXXXXX(x00)0	Yes	No
OR5	XXXXXXX(xx0)	Yes	No
BR6	XXXXXX(x00)0	Yes	No
OR6	XXXXXXX(xx0)	Yes	No
BR7	XXXXXX(x00)0	Yes	No
OR7	XXXXXXX(xx0)	Yes	No
MAR	x	No	No
MCR	(xx00)0(x000)0(0xx0)X(00xx)X	Yes	No
MAMR	xx001000	Yes	No
MBMR	xx001000	Yes	No
MSTAT	0	Yes	No
MPTPR	0200	Yes	No
MDR	x	No	No
TBSCR	0	Yes	No
TBREFA	x	No	No
TBREFB	x	No	No
RTCSC	00(000x)(000x)	Yes	Yes
RTC	x	No	Yes
RTSEC	x	No	Yes
RTCAL	x	No	No
PISCR	0	Yes	No
PITC	x	No	No
PITR	x	N/A	N/A
SCCR	0(000?)(?000)(0??0)0000	Yes	No
PLPRCR	???0(0100)000	Yes	Yes
RSR	0	Yes	Yes

Table 2. (continued)

Register	POR Value	Affected by HRESET	Affected by SRESET
TBSCRK	x	Yes	Yes
TBREFAK	x	Yes	Yes
TBREFBK	x	Yes	Yes
TBK	x	Yes	Yes
RTCCK	x	Yes	Yes
RTCK	x	Yes	Yes
RTSECK	x	Yes	Yes
RTCALC	x	Yes	Yes
PISCRK	x	Yes	Yes
PITCK	x	Yes	Yes
SCCRK	x	Yes	Yes
PLPRCRK	x	Yes	Yes
RSRK	x	Yes	Yes
I2MOD	0	Yes	Yes
I2ADD	x	No	No
I2BRG	FFFF	Yes	No
I2COM	0	Yes	Yes
I2CER	0	Yes	Yes
I2CMR	0	Yes	Yes
SDAR	x	No	No
SDSR	0	Yes	Yes
SDMR	0	Yes	Yes
IDSR1	0	Yes	Yes
IDMR1	0	Yes	Yes
IDSR2	0	Yes	Yes
IDMR2	0	Yes	Yes
CIVR	0	Yes	Yes
CICR	0	Yes	No
CIPR	0	Yes	Yes
CIMR	0	Yes	Yes
CISR	0	Yes	Yes
PADIR	0	Yes	No
PAPAR	0	Yes	No

Table 2. (continued)

Register	POR Value	Affected by HRESET	Affected by SRESET
PAODR	0	Yes	No
PADAT	x	No	No
PCDIR	0	Yes	No
PCPAR	0	Yes	No
PCSO	0	Yes	No
PCDAT	x	No	No
PCINT	0	Yes	No
PDDIR	0	Yes	No
PDPAR	0	Yes	No
PDDAT	x	No	No
TGCR	0	Yes	Yes
TMR1	0	Yes	Yes
TMR2	0	Yes	Yes
TRR1	FFFF	Yes	Yes
TRR2	FFFF	Yes	Yes
TCR1	0	Yes	Yes
TCR2	0	Yes	Yes
TCN1	0	Yes	Yes
TCN2	0	Yes	Yes
TMR3	0	Yes	Yes
TMR4	0	Yes	Yes
TRR3	FFFF	Yes	Yes
TRR4	FFFF	Yes	Yes
TCR3	0	Yes	Yes
TCR4	0	Yes	Yes
TCN3	0	Yes	Yes
TCN4	0	Yes	Yes
TER1	0	Yes	Yes
TER2	0	Yes	Yes
TER3	0	Yes	Yes
TER4	0	Yes	Yes
CPCR	0	Yes	Yes
RCCR	0	Yes	No

Table 2. (continued)

Register	POR Value	Affected by HRESET	Affected by SRESET
RCTR1	NA	Yes	Yes
RCTR2	NA	Yes	Yes
RCTR3	NA	Yes	Yes
RCTR4	NA	Yes	Yes
RTER	0	Yes	Yes
RTMR	0	Yes	Yes
BRGC1	0	Yes	No
BRGC2	0	Yes	No
BRGC3	0	Yes	No
BRGC4	0	Yes	No
GSMR_L1	0	Yes	Yes
GSMR_H1	0	Yes	Yes
PSMR1	0	Yes	Yes
TODR1	0	Yes	Yes
DSR1	7E7E	Yes	Yes
SCCE1	0	Yes	Yes
SCCM1	0	Yes	Yes
SCCS1	0	Yes	Yes
GSMR_L2	0	Yes	Yes
GSMR_H2	0	Yes	Yes
PSMR2	0	Yes	Yes
TODR2	0	Yes	Yes
DSR2	7E7E	Yes	Yes
SCCE2	0	Yes	Yes
SCCM2	0	Yes	Yes
SCCS2	0	Yes	Yes
GSMR_L3	0	Yes	Yes
GSMR_H3	0	Yes	Yes
PSMR3	0	Yes	Yes
TODR3	0	Yes	Yes
DSR3	7E7E	Yes	Yes
SCCE3	0	Yes	Yes
SCCM3	0	Yes	Yes

Table 2. (continued)

Register	POR Value	Affected by HRESET	Affected by SRESET
SCCS3	0	Yes	Yes
GSMR_L4	0	Yes	Yes
GSMR_H4	0	Yes	Yes
PSMR4	0	Yes	Yes
TODR4	0	Yes	Yes
DSR4	7E7E	Yes	Yes
SCCE4	0	Yes	Yes
SCCM4	0	Yes	Yes
SCCS4	0	Yes	Yes
SMCMR1	0	Yes	Yes
SMCE1	0	Yes	Yes
SMCM1	0	Yes	Yes
SMCMR2	0	Yes	Yes
SMCE2	0	Yes	Yes
SMCM2	0	Yes	Yes
SPMODE	0	Yes	Yes
SPIE	0	Yes	Yes
SPIM	0	Yes	Yes
SPCOM	0	Yes	Yes
PIPC	0	Yes	No
PTPR	0	Yes	No
PBDIR	xxx(xx00)0000	Yes	No
PBPAR	xxx(xx00)0000	Yes	No
PBODR	0	Yes	No
PBDAT	x	Yes	Yes
SIMODE	0	Yes	Yes
SIGMR	0	Yes	No
SISTR	0	Yes	No
SICMR	0	Yes	Yes
SICR	0	Yes	No
SIRP	0	Yes	Yes

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